

Remarks & Arguments

In the Office Action, the Examiner noted that Claims 17-20 and 27-55 are pending in the application, Claims 17-20 and 27-34 are withdrawn from consideration and that Claims 35-55 are rejected. By this amendment, Claims 35, 37, 38, 41, 44 and 50-52 have been amended. Thus, Claims 17-20 and 27-55 are pending in the application. The amendments to the claims do not add new matter to the application. The Examiner's rejections are traversed below.

Claim Objections

Claims 35-55 are objected to because of various informalities. The amendments to Claims 35, 37, 38, 41, 44 and 50-52 render the objection moot.

Rejections Under 35 USC 102 and 103

Claims 35 and 38-43 stand rejected under 35 USC 103(a) as being obvious in view of Yoshigai (6,191,045) and Kugimiya (6,277,763). With regard to independent Claim 35 as amended, the Applicant respectfully asserts that Yoshigai and Kugimiya both fail to teach or suggest depositing a conductive adhesive layer between a substrate and a conductive layer. Thus, neither Yoshigai nor Kugimiya teach or suggest that the conductive adhesive layer has a minimum thickness required to provide adhesion between the substrate and the conductive layer for a robust structure that can withstand subsequent processing. Hence, Claim 35 is patentably distinguishable over Yoshigai, Kugimiya and the combination thereof. Claims 38-43 depend

upon Claim 35 and incorporate all the limitation therein. Therefore, Claims 38-43 are patentable for the same reasons advance in support of Claim 35. Claims 36 and 37 are also dependent upon Claim 35 and incorporate all the limitation therein. Therefore, Claims 36 and 37 are also patentable for the same reasons advance in support of Claim 35.

Claims 44-55 stand rejected under 35 USC 103(a) as being obvious in view of Yoshigai, Kugimiya and Mui (6,037,265). With regard to independent Claim 44 as amended, the Applicant respectfully asserts that Yoshigai and Kugimiya fail to teach or suggest that the substrate comprises a first material selected from the group consisting of silicon oxide, silicon nitride and aluminum oxide. Applicant also asserts that Yoshigai, Kugimiya and Mui fail to teach or suggest that the conductive adhesive layer adheres the conductive layer to the substrate. Yoshigai, Kugimiya and Mui also fail to teach or suggest forming a bit-line gate by selectively etching a portion of the conductive layer and a portion of the conductive adhesive layer without sacrificing the substrate utilizing a plasma, wherein the plasma comprises a chlorine or oxygen etchant and wherein an ion flux of the plasma is a function of a first power source and an energy of the plasma is a function of a second power source. Hence, Claim 44 is patentably distinguishable over Yoshigai, Kugimiya, Mui and the combination thereof. Claims 45-51 depend upon Claim 44 and incorporate all the limitation therein. Therefore, Claims 45-51 are patentable for the same reasons advance in support of Claim 44.

With regard to independent Claim 52 as amended, the Applicant respectfully asserts that Yoshigai, Kugimiya and Mui fail to teach or suggest depositing a polysilicon layer on an ONO

layer and a conductive layer of tungsten or tungsten silicide on the polysilicon layer. Applicant also asserts that Yoshigai, Kugimiya and Mui fail to teach or suggest that the polysilicon layer has a thickness of 500 angstrom or less to provide adhesion between the ONO layer and the conductive layer for a robust structure that can withstand subsequent processing. Yoshigai, Kugimiya and Mui also fail to teach or suggest selectively etching the conductive layer and the polysilicon layer without sacrificing the ONO layer utilizing a decoupled plasma. Hence, Claim 52 is patentably distinguishable over Yoshigai, Kugimiya, Mui and the combination thereof. Claims 53-55 depend upon Claim 52 and incorporate all the limitation therein. Therefore, Claims 53-55 are patentable for the same reasons advance in support of Claim 44.

Conclusion

For all the reasons advanced above, Applicant respectfully submits that the present application is in condition for allowance and that action is earnestly solicited. The Examiner is invited to contact Applicant's undersigned representative if the Examiner believes such action would expedite resolution of the present Application.

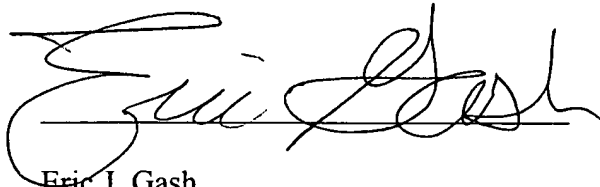
The Commissioner is hereby authorized to charge any additional fees, which may be required for this amendment, or credit any overpayment, to Deposit Account 23-0085. In the event that an extension of time is required, or may be required in addition to that requested in a petition for an extension of time, the Commissioner is requested to grant a petition for that extension of time which is required to make this response timely and is hereby authorized to

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charge any fee for such an extension of time or credit any overpayment for an extension of time
to Deposit Account 23-0085.

Respectfully submitted,

WAGNER, MURABITO & HAO, LLP

A handwritten signature in black ink, appearing to read "Eric J. Gash", written over a horizontal line.

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